

**REMARKS**

By this Amendment claim 9 has been amended. Accordingly, claims 1-20 are pending in the present application.

Claims 1, 5, 8-10, 13, 15, 16, 17 and 20 stand rejected under 35 U.S.C. §102(b) as being anticipated by U.S. Patent No. 6,400,239 to Chun et al. Claims 1-3, 5, 6, 8, 17, 18 and 20 stand rejected under 35 U.S.C. §102(b) as being anticipated by U.S. Patent No. 5,374,910 to Yamagata. Claims 3, 4, 7, 11, 12, 18 and 19 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Chun et al. Claims 2, 6 and 14 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Chun et al. in view of Yamagata. Claims 4 and 19 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Yamagata. Applicants respectfully traverse these rejections.

Among the limitations of independent claims 1, 9 and 17 which are neither disclosed nor suggested in the prior art of record is a conductive cover for a dielectric duplexer which includes a bent portion defining a first part and a second part, and at least one inwardly projecting portion positioned “along the bent portion.” In other words, the inwardly projecting portion is located along the fold line separating the first part and second part of the cover. One of the advantages to locating the inwardly projecting portion along the bent portion is that it increases the strength of the bent portion so that the conductive cover can not easily be deformed and thus decrease its electromagnetic shielding effect. See, for example, page 3, lines 12-15 of the specification.

While Chun et al. shows that its conductive cover has inwardly projecting embossed portions 250, they are not located along the bent portion (i.e., the fold line separating the shielding surface and the adhering surface of the conductive cover), and thus can not increase the strength of the bent portion. In other words, the bending angle of the conductive cover 200 of Chun et al. can still be easily deformed by some external force

during further manufacturing steps. The embossed portions of Chun et al. are merely used to provide for the alignment and spacing of the conductive cover from the open circuit surface of the dielectric block. See col. 3, line 64 through col. 4, line 2 of Chun et al. In fact, inasmuch as Chun et al. shows that the embossed portions 250 are disposed along the adhering surface of the cover, it teaches away from the present invention as defined in independent claims 1, 9 and 17.

Similarly, the conductive cover of Yamagata has inwardly projecting portions 33A and 33B. These inwardly projecting portions, however, are not located along the bent portion. As described at col. 6, lines 5-7, the inwardly-bent partitions 33A and 33B are formed from the upper wall of the case 3. Thus, inwardly projecting portions 33A and 33B can not increase the strength of the bent portion. Moreover, inasmuch as Yamagata shows that the projecting portions 33A and 33B project inwardly from the upper wall of the case 3, it also teaches away from the present invention as defined in independent claims 1, 9 and 17.

Therefore, even if one were to combine the teachings of Chun et al. and Yamagata, one would not arrive at the present invention as defined in independent claims 1, 9 and 17. At best, one would arrive at a conductive cover having inwardly projecting portions which are not positioned along the bent portion of the cover. Accordingly, it is respectfully submitted that independent claims 1, 9 and 17 patentably distinguish over the art of record.

Claims 2-8 each depend directly from independent claim 1 and include all of the limitations found therein. Claims 10-16 each depend directly from independent claim 9 and include all of the limitations found therein. Claims 18-20 each depend directly from independent claim 17 and include all of the limitations found therein. Each of these dependent claims include additional limitations which, in combination with the limitations

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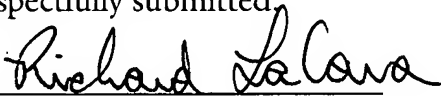
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of the claims from which they depend, are neither disclosed nor suggested in the art of record. Accordingly, claims 2-8, 10-16 and 18-20 are likewise patentable.

In view of the foregoing, favorable consideration of the amendments to claim 9, and allowance of the present application with claims 1-20 is respectfully and earnestly solicited.

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Respectfully submitted,

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